

BENCHTOP COATING REMOVAL

RemUVA benchtop powder abrasion system is designed to remove conformal coatings, including UV40, from finished assemblies. Has a fully configurable nozzle to permit working on smaller areas or to remove coating across a larger area. Reportedly does not damage adjacent devices, interconnects or PCBs. Is equipped with adjustable powder flow control and air pressure regulation. Uses a point ionizer to reduce ESD from reaching levels that could potentially damage components.

HumiSeal

humiseal.com



GOLD BALL BONDER

Q2119A fine-pitch, fine-wire (17-75 μm) automatic gold ball bonder is for smaller lot sizes, multiple product variations and frequent setup changes. Interface provides point-and-click bonding; unlimited wires; easy bond process editing; extensive program storage; bond parameter library. Optional programmable ultrasonic generator (256 increments) with low impedance transducers, programmable temperature controllers (optional dual-loop), application-specific software, and custom machines with tables up to 300 x 300 mm.

Questar Products International

questarproducts.com



PCB PROFILING KIT

The Profiling Kit contains all necessary accessories for profiling a PCB, including thermocouples, aluminum tape, gloves, scissors, pick and more.

KIC

kicthermal.com

OTHERS OF NOTE

LOW-VOLUME WAVE SOLDERING

GoWave 1030 wave soldering system is for low-volume production for both leaded and Pb-free applications. Is for soldering small- or medium-size batches. Now features a longer reflection tunnel over both the preheat area and the solder pot. Has been redesigned as one unit. Features a new spray flux nozzle with HVLP technology. Has a PCS 707 touchscreen controller and USB interface. Service points for the fluxer and compressed air are now located directly at the inlet section of the machine.

Seho Systems

sehona.com

'ICT TESTABLE' SAC PASTES

S3X58-M650 solder paste is an ICT testable, halogen-free SAC 305 alloy. Properties include low voiding, high print speeds, and 0.4 mm pitch μBGA capability. S3X70-M407 Pb-free no-clean solder paste for ultra-fine-pitch applications uses a Type 5 powder; has been formulated for 0.2 mm pitch μBGA devices and 01005 components. Is said to wet in air environments and is low voiding.

Koki Co. Ltd.

ko-ki.co.jp

METER-MIX DISPENSE SYSTEM

See-Flo 1100 is a fixed-ratio, positive displacement system for manual and automated adhesive and sealant applications. Meters low- to high-viscosity two-component materials, such as epoxies, urethanes, silicones and acrylics supplied by pumps or pressure tanks. Can be floor- or mobile-cart mounted, and may be integrated with a dispensing robot assembly. For dispensing continuous precision beads.

Sealant Equipment & Engineering

sealantequipment.com

LOWER-VISCOSITY POPPET VALVE

Tridak Model 785 dispenses low-to-medium viscosity materials, such as adhesives, silicones, and other filled materials. Design minimizes friction between the actuating components of the valve and the material being dispensed. The stroke adjustment and control feature offers precise adjustment of fluid deposit volume and flow. Material is shut off cleanly at the end of each cycle. Peak performance is obtained when actuated with Tridak Model 345 valve controller.

Tridak

tridak.com

TRIPLE-SPAN RADIAL MACHINE

The 5.0/7.5/10.0 mm system has large span capacity that reportedly virtually eliminates manual assembly requirements. Features 10 mm tooling for the Radial 8XT. Comes in standalone and pass-through configurations. A 15 mm dispense head tooling is offered.

Universal Instruments

uic.com

3D VISION SOFTWARE

3D-Locate delivers real-time 3D position information that enables automation equipment to work with a variety of parts, stacked or tilted items. Is said to improve vision performance for applications such as logistics, robot-guided de-palletizing and precision assembly. Can be used in combination with Cognex code reading, gauging, and inspection tools. For use in single camera or multiple camera applications, and dimensioning, sorting and picking on conveyor lines.

Cognex

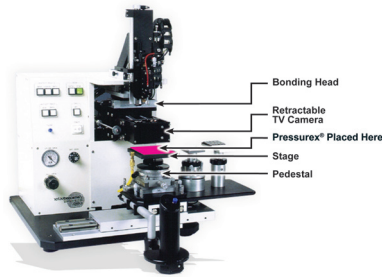
cognex.com



'LOWER POWER' WAVE SOLDERING

EWS-310 has continuous PCB width adjustment; accommodates boards up to 12" or 310 mm in width. Total power consumption said to be 10% less than comparable models. Employs a durable "L" finger handling mechanism.

APS Novastar
apsgold.com



THIN FLEXIBLE SENSOR FILM

Pressurex reveals pressures from 2 - 43,200 PSI. When placed between the contacting surfaces of a flip chip bonder, it changes color directly proportional to the amount of pressure applied. Precise pressure magnitude and distribution is then determined by comparing color variation results to a color correlation chart.

Sensor Products Inc.
sensorprod.com/pressurex



DOUBLE-LAYER PLATINUM STENCIL

VectorGuard is for semiconductor applications and component manufacture. Is fabricated through a two-step lithography and nickel-electroforming process. Mesh layer holds the stencil intact. Circuit layer determines the thickness and shape of print deposits. Is for solar cell manufacture or LTCC manufacture. Reportedly prints long conductive lines without diminishing stencil strength. Combines filling and innerlayer printing stages. Dimensional accuracy said to be better than 0.1 µm/mm.

DEK
dek.com

OTHERS OF NOTE

SPC FOR SPI

Statistical Process Control software tracks manufacturing data and presents in pie charts, pareto charts, etc. using different parameters, including pad size, part number, pad shape, part type, by PCB supplier and other metrics. Can be used on or offline. Generates reports without stopping production with constant, automatic updates as an optional function.

Koh Young Technology
kohyoung.com

HEAVY DUTY VACUUM TWEezer

VC-3 is self-contained and activates from the top via a plunger mechanism. Is an ESD-safe unit and is said to eliminate contamination from skin oils and handling damage to leads. Is for loading burn-in trays or tinning leads, and can handle larger packages. Includes 1/2" diameter heavy-duty vacuum pen and two handling tips, a 1/2" and a 5/8" diameter rubber vacuum cup.

Virtual Industries Inc.
virtual-ii.com

BATH ALKALINITY SOLUTION

Zestron Bath Analyzer 10 and 20 now come in 5-liter containers. Have been formulated to measure the concentration and indicate alkalinity of baths containing Atron, Vigon and cleaning agents. Developed as an alternative to the Refractive Index method; are designed to monitor chemical bath concentrations irrespective of dissolved organics.

Zestron
zestron.com

AOI SOFTWARE ENHANCEMENTS

Software tools are available for a very high-resolution camera module that provides measurements of balls and wedges. Reportedly measures 25 µm gold thin-wire wedge sizes with a standard deviation of 1 µm. Inspects qualitative characteristics of wire bonds; balls and wedges statistical evaluation and trend analysis of critical geometric dimensions can be performed. For gold wire bonds with diameters less than 25 µm, the VHR module's illumination enhances geometric features. Resolution of approximately 3 µm per pixel produces standard deviations in wedge widths of 1 µm.

Viscom
viscom.com

IC TO AL SUBSTRATE THICK FILM

A thick film dielectric and conductor system improves the mounting of silicon ICs to aluminum substrates. Provides low thermal resistance between chip and heatsink. Glass system of the Pb- and Cd-free dielectric paste offers thermal conductivity on both 3003- and 6061-grade alloy aluminum substrates. Reduces bowing by closely matching Al CTE. Also, a Pb-free silver conductor paste, fired together at 550°C with the dielectric paste, provides solderability and adhesion. Is for applications such as direct-mounted LEDs.

Heraeus Thick Films Materials Business Unit
heraeus.com

SELECTIVE SOLDERING WITH NITROGEN SPOT PREHEAT

KISS selective soldering machine now comes with nitrogen spot preheating. Focuses and controls superheated nitrogen delivery to a small, user-defined area. Is for soldering operations where large area bottom-side or topside preheating is not feasible.

ACE Production Technologies
ace-protect.com